

IN THE CLAIMS

Please amend the following claims:

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Claims 1-7 (cancelled)

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8. (currently amended) A heat spreader for an IC circuit package, comprising:  
a thermally conductive heat spreader body having a first surface  
~~configured to thermally coupled the heat spreader to an abutting IC die; and~~  
a coating of organic surface protectant on the first surface and wherein the coating  
directly abuts the IC die.
9. (original) A heat spreader as claimed in claim 8, wherein the body comprises copper.
10. (previously amended) A heat spreader as claimed in claim 8, wherein the organic surface protectant comprises one or more imidazole compounds.
11. (original) A heat spreader as claimed in claim 8, wherein the organic surface protectant comprises one or more triazole compounds or salts thereof.
12. (original) A heat spreader as claimed in claim 8, wherein the coating completely envelops the body.
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13. (currently amended) An IC package, comprising:  
a package substrate;  
an IC die attached to the substrate;  
a heat spreader body having a first surface thermally coupled to ~~and abutting~~ the  
IC die; and

a coating of organic surface protectant disposed on ~~between~~ the first surface and wherein the coating directly abuts the IC die.

14. (original) An IC package as claimed in claim 13, wherein the coating completely envelops the body.

15. (original) An IC package according to claim 13, further comprising a thermal interface material between the IC die and the coated first surface of the heat spreader.

16. (original) An IC package according to claim 15, wherein the thermal interface material is a solder or solder-polymer hybrid.

17. (original) An IC package according to claim 13, wherein the body comprises copper.

18. (original) An IC package according to claim 13, wherein the organic surface protectant comprises one or more triazole compounds or salts thereof.

19. (previously amended) An IC package according to claim 13, wherein the first surface is coated with a metal.

20. (currently amended) A printed circuit board assembly comprising:

a printed circuit board,

an IC die electronically coupled to the printed circuit board, and

a heat spreader body having a first surface thermally coupled to ~~and abutting~~ the IC die; and

a coating of organic surface protectant disposed on ~~between~~ the first surface and wherein the coating directly abuts the IC die.

21. (original) A printed circuit board assembly as claimed in claim 20, further

comprising a thermal interface material between the IC die and the coated first surface of the heat spreader, wherein the thermal interface material is a solder or solder-polymer hybrid.

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22. (original) A printed circuit board assembly as claimed in claim 20, wherein the IC die is directly attached to the printed circuit board.

23. (original) A printed circuit board assembly as claimed in claim 20, wherein the IC die is attached to a package substrate that is attached to the printed circuit board.

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